

Abstract

Method for producing printed circuit boards having coarse conductor structures and at least one region having fine conductor structures

The coarse conductor structures (GL) and the fine conductor structures (FL) are etched out of a metal layer in a common etching process, an etching resist patterned by means of photolithography being used in the region of the coarse conductor structures (GL) and an etching resist patterned with the aid of a laser beam being used in the region of the fine conductor structures.

Figure 1